This Sheet Has Been Replaced



ABSTRACT

SHEET REMOVING APPARATUS AND METHOD

A protecting sheet applied to a wafer is removed by using an adhesive tape with a prescribed length, by bonding the adhesive tape to an edge portion of the protecting sheet and then pulling the adhesive tape. During pulling, a guide roller is held in contact with the protecting sheet and, while the guide roller is held in a fixed position, a peeling head portion and a table are moved in the opposite direction with each other to thereby remove the protecting sheet.

(Figure 1)